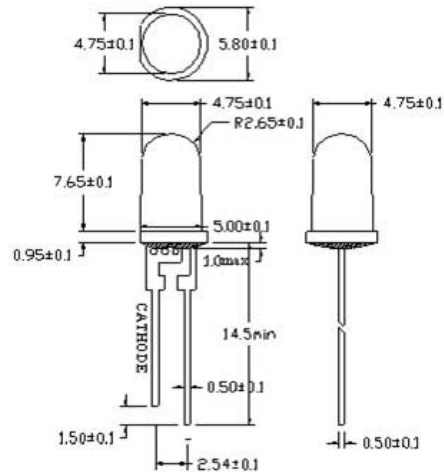


Part Number: BUWLC5333W50BB25

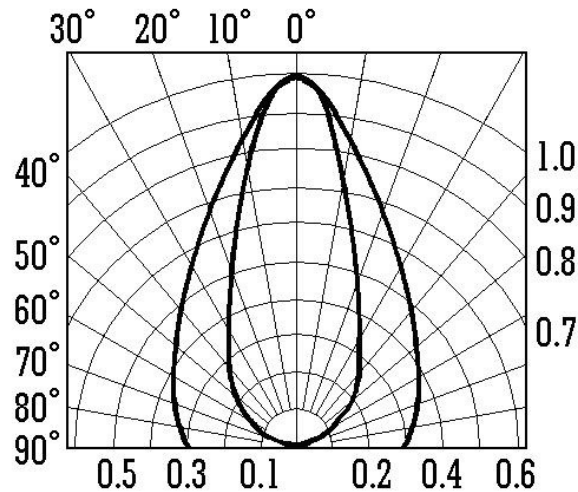
ULTRA PURE WHITE

5333 5mm SERIES 5 Chips ROUND LED LAMPS

Package Dimension



Radiation Diagram



Viewing Angle - $2\Phi \frac{1}{2} : 50^\circ \pm 10^\circ$

Features:

- ✓ Built-in 5 Power Chips for up to 100mA Operation
- ✓ Low Power Consumption
- ✓ Longer Life Time
- ✓ I.C. Compatible

Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Maximum	Unit
DC forward current	I_F	100	mA
Peak forward current Pulse width Max. 10ms duty ratio Max 1/10	I_{FP}	200	mA
Reverse Voltage	V_R	5	V
Power dissipation	P_D	400	mW
Operating Temperature	T_{OPR}	-40 ~ +85	°C
Storage Temperature	T_{STG}	-40 ~ +100	°C
Soldering Temperature	T_{SDR}	260°C for 5sec	°C

Electrical: Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	Min	Typ	Max	Unit
DC forward voltage	V_F	$I_F = 100\text{mA}$	2.8	3.6	4.0	V
DC reverse current	I_R	$V_R = 5\text{V}$	-	-	100	μA
Intensity luminous	I_v	$I_F = 100\text{mA}$	12000	-	18000	mcd
Lumen Rating	I_m	$I_F = 100\text{mA}$	10	15	20	lm
Color Temperature	C_T	$I_F = 100\text{mA}$	-	-	10000	K

Notes:

- All dimensions are in millimeters.
- Clean only in isopropanol, ethanol, Freon TF (or equivalent).
- If forming is required, it must be done before soldering. Form pin leads by securing under 5mm from body and bedding with radio pliers or the equivalent to avoid pressure on resin. When the LED is mounted into a P.C. board, pitch spacing should be aligned to prevent any stress to the resin. Any unsuitable stress applied to resin may break bonding wire in LED, which will cause failure.
- Protruded resin under flange is 1.5mm Max.
- Specifications are subject to change without notice.

Version: V1.0